

# Si7252ADP-VB Datasheet Dual N-Channel 100V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>		
100	0.018at V <sub>GS</sub> = 10 V	35		
	$0.022$ at $V_{GS} = 4.5 \text{ V}$	36		

#### **FEATURES**

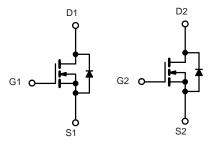
- 175 °C Junction Temperature
- Trench technology Power MOSFET
- Material categorization:







Top View



N-Channel MOSFET

N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V <sub>GS</sub>	±20	V			
Continuous Drain Current (T <sub>.1</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	l-	35			
Continuous Drain Current (1) = 175 °C)	T <sub>C</sub> = 100 °C	- I <sub>D</sub>	20 <sup>a</sup>			
Pulsed Drain Current	I <sub>DM</sub>	105	Α			
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	76 <sup>a</sup>				
Avalanche Current	I <sub>AS</sub>	82	-			
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	110	mJ		
Maximum Power Dissination	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	W		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	'D	3 <sup>b</sup> , 8.3 <sup>b, c</sup>	]		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Mariana lunation to Ambianta	t ≤ 10 sec	R <sub>thJA</sub>	15	18	°C/W		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		60	50			
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1			

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static			L				
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100		V		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	1 V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 30V, V_{GS} = 0 V$			1	μА	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 30V, V_{GS} = 0 V, T_{J} = 125  ^{\circ}C$			50		
		$V_{DS} = 30V, V_{GS} = 0 V, T_{J} = 175  ^{\circ}C$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.018			
D : 0	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.008		Ω	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.010			
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 12A		0.022			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic							
Input Capacitance	C <sub>iss</sub>			3900		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}$		470			
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	Qg			89	70	nC	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		26			
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			23			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			21	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, R_L = 0.6 \Omega$ $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		15	25	no	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			35	50	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				105	Α	
Diode Forward Voltage	$V_{SD}$	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		4	135	ns	

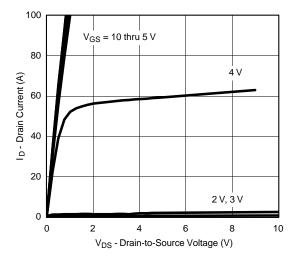
#### Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- c. Independent of operating temperature.

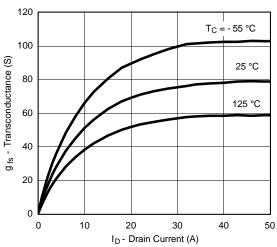
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



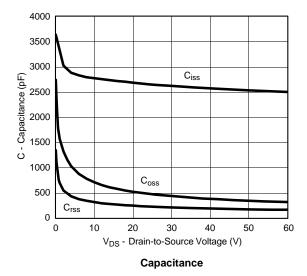
#### TYPICAL CHARACTERISTICS (25 °C unless noted)



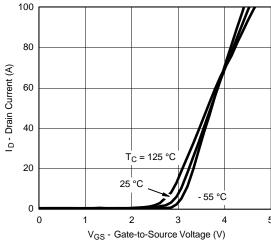
#### **Output Characteristics**



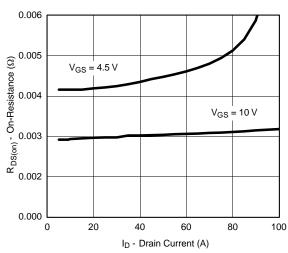
#### Transconductance



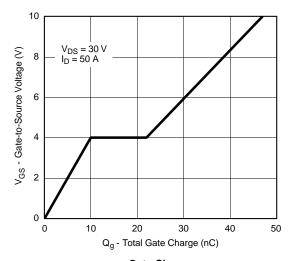
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#### **Transfer Characteristics**



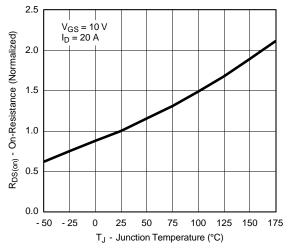
#### On-Resistance vs. Drain Current



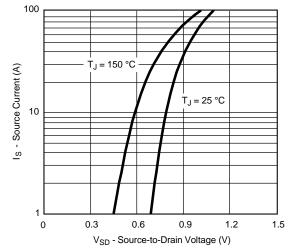
Gate Charge



#### TYPICAL CHARACTERISTICS (25 °C unless noted)



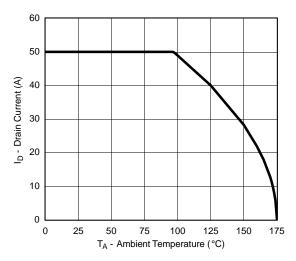
On-Resistance vs. Junction Temperature

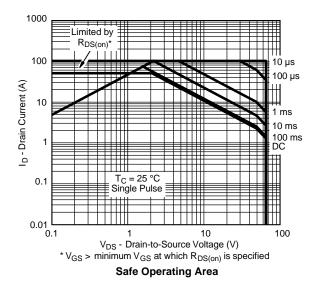


Source-Drain Diode Forward Voltage

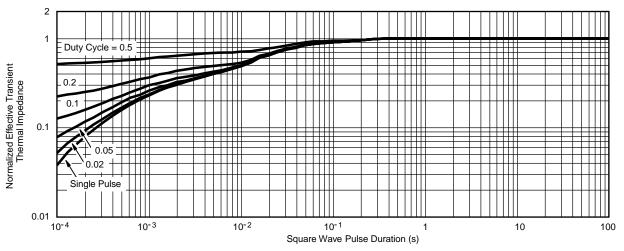


#### THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



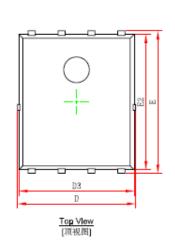
Normalized Thermal Transient Impedance, Junction-to-Case

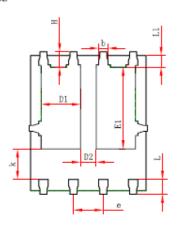
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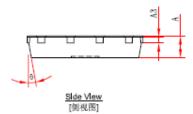


#### PDFNWB5×6-8L-A PACKAGE OUTLINE DIMENSIONS





Bottom View [背视图]



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	0.254 REF.		REF.	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	1.470	1.870	0.058	0.074	
D2	0.470	0.870	0.019	0.034	
E1	3.375	3.575	0.133	0.141	
D3	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
e	1.270TYP.		0.050TYP.		
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	



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